



<b>Model VG202MKII</b>	
No. of Spindle	: 2
No. of Vacuum chuck	: 1
Spindle Motor	: 2.2 Kw
Grinding Mode	: Gauge
Work spindle Motor	: 1 Kw
Wafer size to grind	: 4/5/6 & 8"
Bearing type	: Air (both)

**High Precision Back Grinder**  
**Model VG202MKII**

**Full-Automatic Wafer Grinder for SOI application**

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## FEATURES

Model VG202MKII precision grinder is designed to meet the increasingly tighter geometric and surface finish requirements. Total thickness Variation (TTV) of less than 1µm can be easily achieved to meet tomorrow's Silicon On Insulator (SOI), Direct Wafer Bonding (DWB), and Silicon Fusion Bonding (SFB) wafer bonding technology. Optional loader system with robot allows for one cassette to be processed in full-automatic.

## SPECIFICATIONS

Maximum wafer-machining diameter of wafer	Ø8" (universal sizes also available)
Grinding Spindle: Bearing type Motor Rapid feed speed Grind feed speed	Air bearing, maximum 3600 rpm 2.2 kw, 4P, high frequency motor 100 mm/min 1 to 999 µm/min
Grinding wheel size	Ø250 (mm)
Work spindle Bearing type	Air Bearing, 1 to 999 rpm
Automatic Sizing Device: Wafer thickness measuring system Wafer minimum setting size Wafer size display range	2 point contact in-process gauge 1 µm ± 1000
Wafer Cleaning Unit	Water + brush, 100 rpm
Control Cabinet CRT Display Programming method Vacuum Pump Unit	Mounted on the main body 9" screen Keyboard 1.5 kw motor, 40 Torrs Exhaust 40 m³/hr Coolant (city) water 5 liter/min
Utilities: Electric Power Cutting Water Consumption Cleaning Water Consumption Coolant water (city water) Air consumption (dry air)	3P, 200V, 15KVA 12 to 15 liter/min 4 liter/cycle 5 liter/min (for vacuum pump) 60 N liter/min (5kg/cm²)
Grinding Accuracy: Wafer thickness variation Wafer to wafer thickness Roughness	Ø6" = 0.65µm or less, Ø8" = 0.80µm or less Ø6" = 0.8µm or less, Ø8" = 1.0 µm or less Rmax = 0.1µm or less

Specifications subject to change without notice.